

Features

- Low operating voltage
- Ultra low leakage
- Low clamping voltage

HF

Mechanical Data

- Case: SOD-323
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



SOD-323

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
GESD33VB3	SOD-323	3000 pcs / Tape & Reel	33

Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (t _p = 8 / 20μs)	P _{PK}	300	W
Peak Pulse Current (t _p = 8 / 20μs)	I _{PP}	5	A
Reverse Working Voltage	V _{RWM}	33	V
ESD According to IEC61000-4-2 Air	V _{ESD}	±30	kV
ESD According to IEC61000-4-2 Contact Discharge	V _{ESD}	±30	kV

Thermal Characteristics

Parameter	Symbol	Value	Unit
Operating Junction Temperature Range	T _J	-55 ~ +125	°C
Storage Temperature Range	T _{STG}	-55 ~ +150	°C

Electrical Characteristics (@ T_C = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA	35	-	40	V
I _R	Reverse Leakage Current	V _{RWM} = 33V	-	-	500	nA
V _C	Clamping Voltage	I _{PP} = 4A, t _p = 8/20μs	-	-	75	V
C _J	Junction Capacitance	V _R = 0V, f = 1.0MHz	-	-	30	pF

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

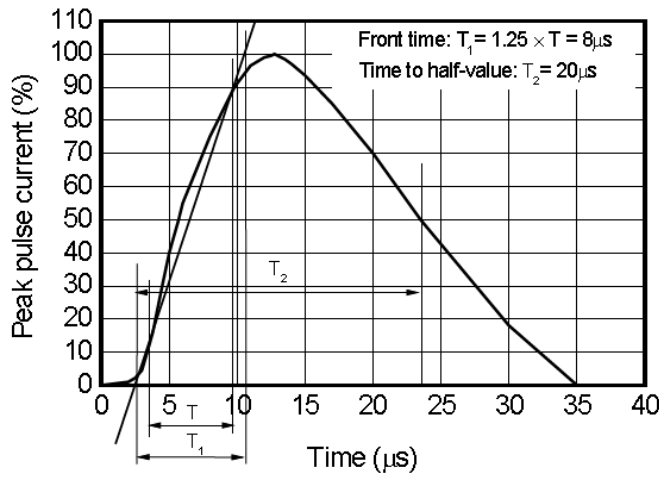


Fig1. 8/20 μs waveform per IEC61000-4-5

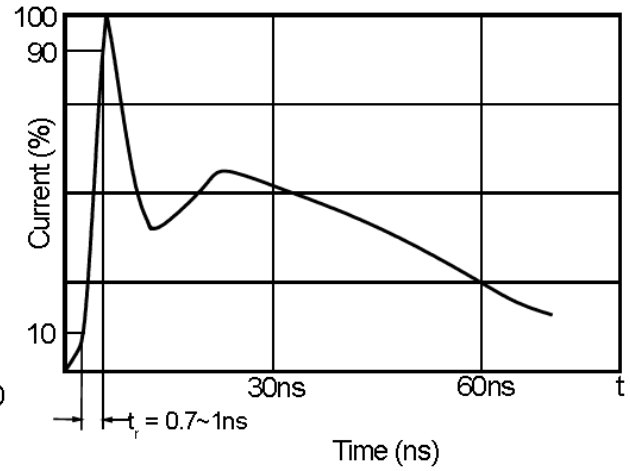


Fig2. ESD pulse waveform according to IEC61000-4-2

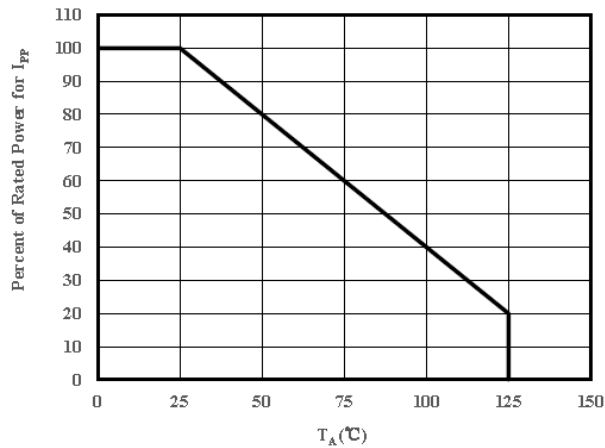
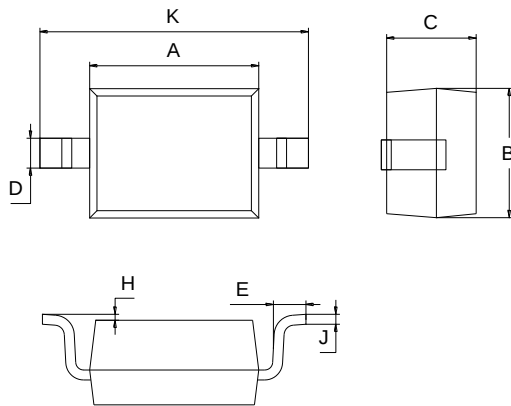


Fig3. Power Derating Curve

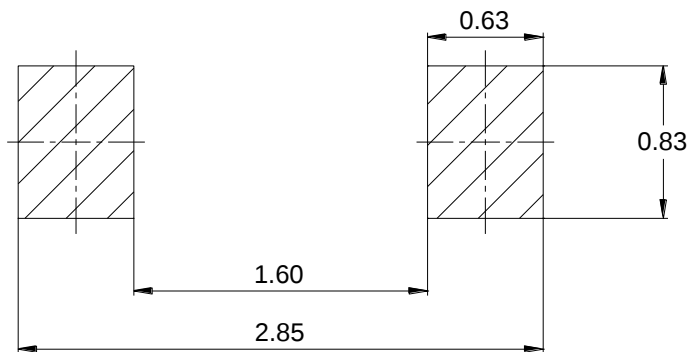
Package Outline Dimensions (Unit: mm)



SOD-323		
Dimension	Min.	Max.
A	1.60	1.80
B	1.20	1.40
C	0.80	0.90
D	0.25	0.35
E	0.22	0.42
H	0.02	0.10
J	0.05	0.15
K	2.55	2.75

Mounting Pad Layout (Unit: mm)

SOD-323



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